

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
31 May 2001 (31.05.2001)

PCT

(10) International Publication Number
WO 01/39268 A1

(51) International Patent Classification⁷: H01L 23/40, H05K 7/12

(21) International Application Number: PCT/US00/28587

(22) International Filing Date: 16 October 2000 (16.10.2000)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/450,080 29 November 1999 (29.11.1999) US

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(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZW.

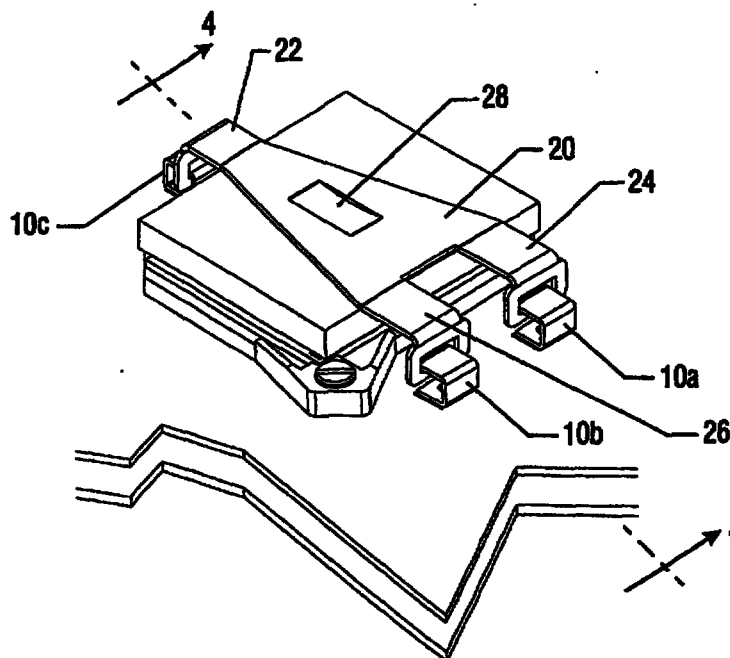
(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

Published:

— With international search report.

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: CLAMPING HEAT SINKS TO CIRCUIT BOARDS OVER PROCESSORS



(57) Abstract: A heat sink (18) may be spring strapped onto a socketed processor (11) using clips (10) that engage the spring strap (20) and that are pre-positioned on the circuit board (14). The clips (10) may be C-shaped and may include an upper spring arm portion (34), a vertical portion (32), and a base (30) which may be surface mounted to the circuit board (14). The upper spring arm (34) of the C-shaped clip (10) then releasably engages the spring strap (20) to clamp the heat sink (18) firmly onto the socketed processor (11).

WO 01/39268 A1